

REMARKS

The Office Action mailed September 26, 2001, has been received and reviewed. Claims 1 through 4 are currently pending in the application. Claims 3 and 4 have been allowed. Claim 1 stands rejected. Claim 2 has been objected to as being dependent upon a rejected base claim, but the indication of allowable subject matter in such claim is noted with appreciation.

Per this response, Applicants have cancelled claim 2, amended claim 1, entered new claims 18 through 26, and respectfully request reconsideration of the application as amended herein.

35 U.S.C. § 102(e) Anticipation Rejection

Anticipation Rejection Based on U.S. Patent No. 5,643,835 Chia et al.

Applicants have amended claim 1 herein to include the subject matter previously set forth in claim 2 which is cancelled herein and which was indicated by the Examiner to include allowable subject matter.

Applicants, therefore, submit that claim 1 is in condition for allowance and respectfully request the same.

ENTRY OF AMENDMENTS

The amendment to claim 1 above should be entered by the Examiner because the amendment is supported by the as-filed specification and drawings and does not add any new matter to the application.

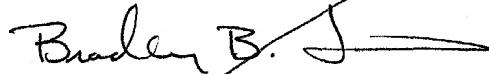
ENTRY OF NEW CLAIMS

New claims 18 through 26 should be entered by the Examiner because they are supported by the as-filed specification and drawings and do not add any new matter to the application. Further, Applicants submit that claims 18 through 26 are in condition for allowance and respectfully request the same.

CONCLUSION

Claims 1, 3, 4 and 18 through 26 are believed to be in condition for allowance, and an early notice thereof is respectfully solicited. Should the Examiner determine that additional issues remain which might be resolved by a telephone conference, the Examiner is respectfully invited to contact Applicants' undersigned attorney.

Respectfully Submitted,



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Enclosure: Version With Markings to Show Changes Made

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

1. (Amended) A method of forming an integrated circuit package, the method comprising:

forming a lead frame having a plurality of conductors and at least one alignment feature electrically isolated from the plurality of conductors;

coupling at least some of the plurality of conductors to a semiconductor die; [and]
encapsulating the semiconductor die and a portion of the lead frame with an insulating material;

and

removing the at least one alignment feature.